

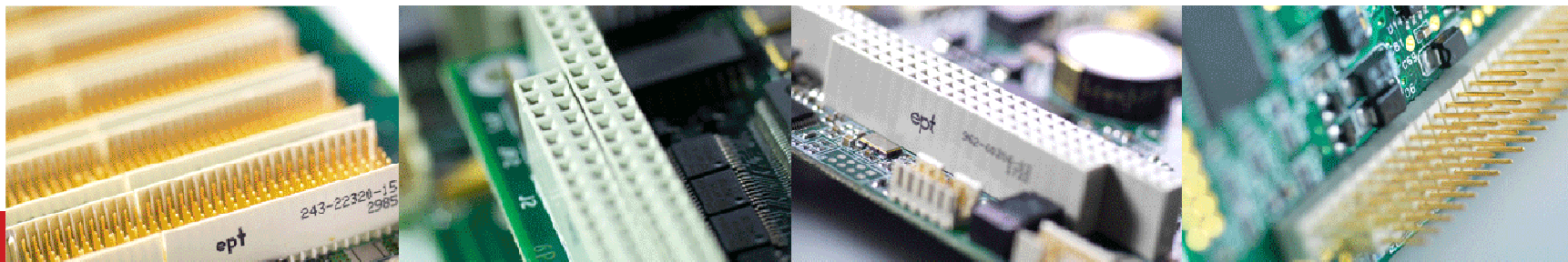
# Press-Fit Technology

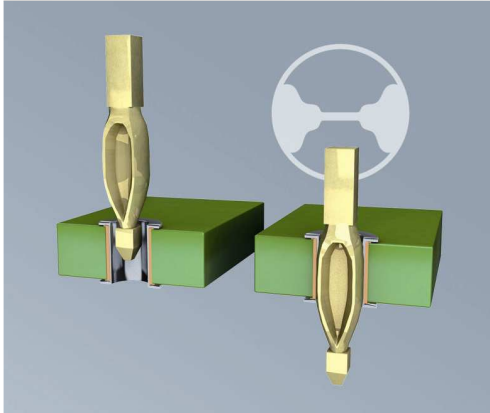
Reliable electrical and mechanical connection

# Agenda



- Technology
- Advantages
- Pillars of the Press-Fit Technology
- Quality

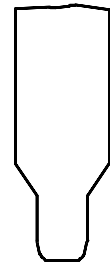
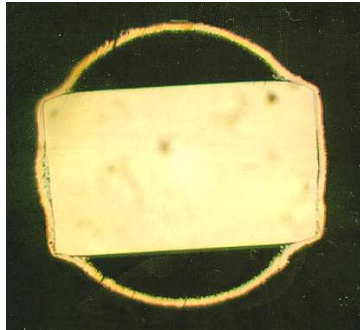




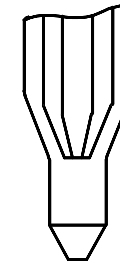
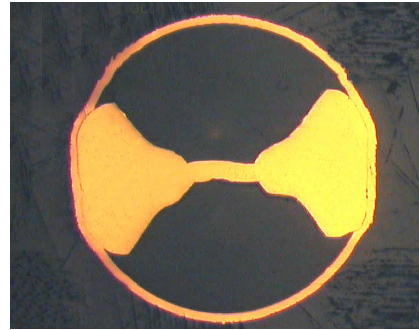
## Press-Fit Technology:

- **solder free electro-mechanical** connection
- force fitting an oversized **contact pin** into the plated through hole of a printed circuit board (PCB)
- **defined and controlled** insertion forces
- a **gas tight** connection is made between the pin and the plated through hole
- press-fit technology belongs to the **most reliable electrical connection** technology.
- **IEC 352-5**

# Flexible / Solid Press-Fit Zone



massiv

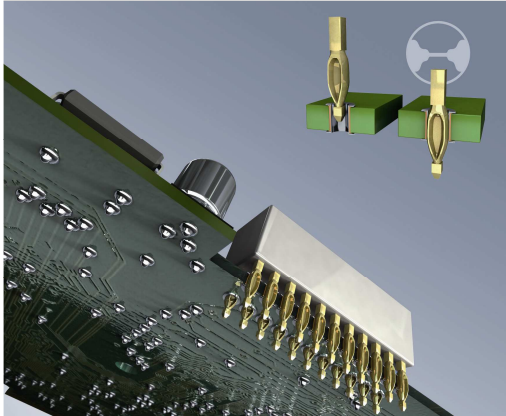


flexibel

## Advantages of the flexible press-fit zone:

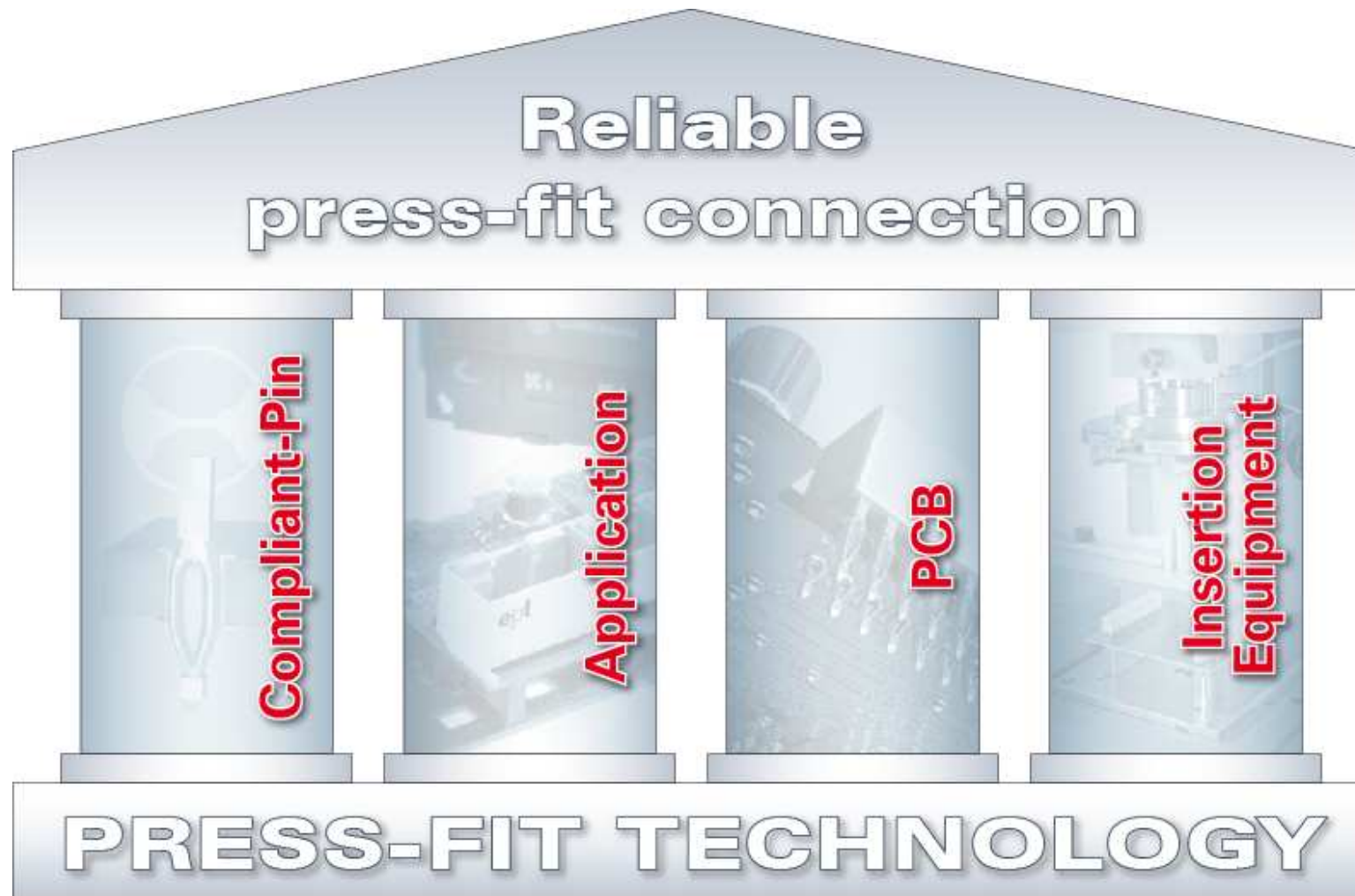
- deformation of the flexible press-fit section prevents excessive deformation of the copper barrel of the PCB
- greater plated through hole tolerances can be specified with flexible press-fit pins
- insertion forces are lower with flexible pins
- multiple press in cycle, for repair, are possible with flexible press-fit sections

# Advantages

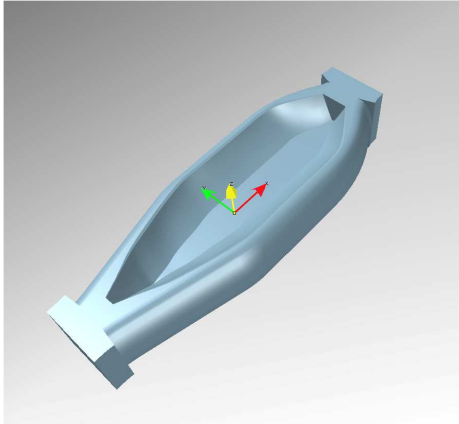


- **No thermal stress** on the PCB
- **No fumes, gases, or cleaning fluids** which may reduce the contact reliability of the connector
- **No cold solder joints**
- No shorts as a result of solder bridging
- Superior **mechanical / electrical connection**
- Fast, **cost effective** and **process stable**, assembly of the connector onto the PCB
- Complete **repairability**
- **Long tail connector pins** can be applied to the PCB without the difficulty in lead soldering
- **High reliability**

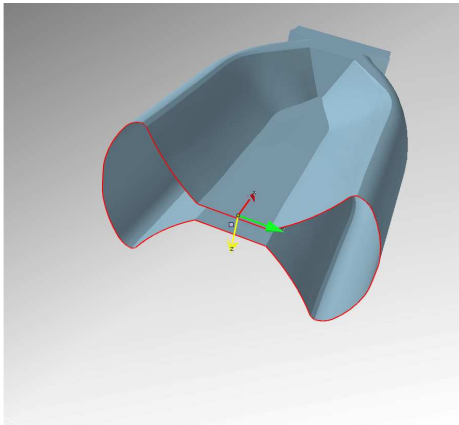
# Pillars of the Press-Fit Technology



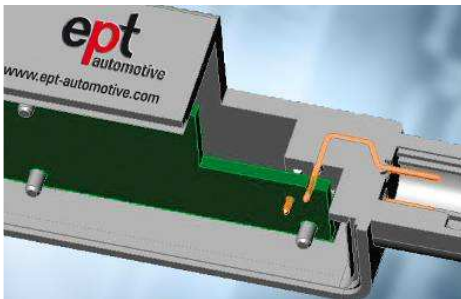
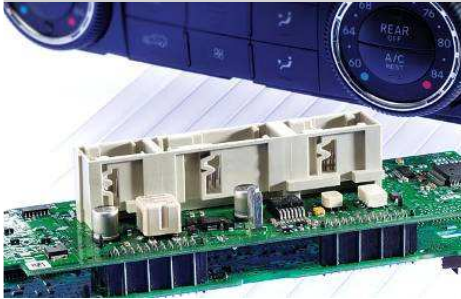
# Compliant-Pin - Parameters



- Design
- Dimension
- Material
- Surface / Plating

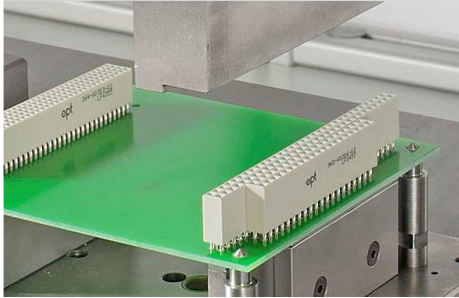


# Application Characteristics

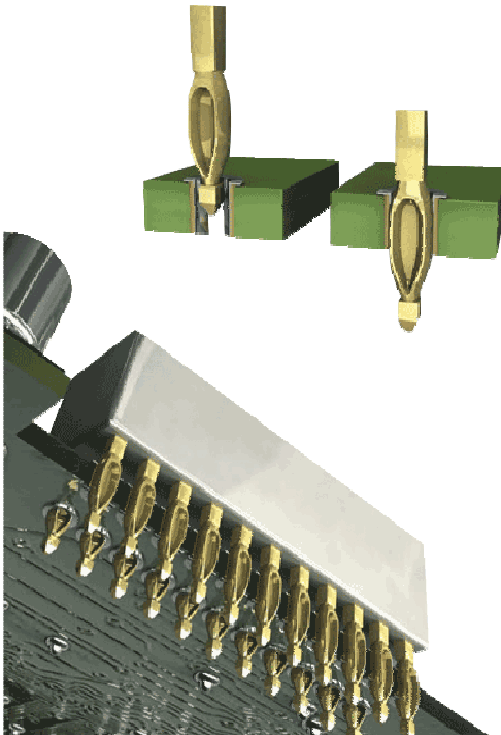


- **Applications** of press-fit technology (automotive, telecom, etc.)
- **Appliances** (Backplane-daughtercard, pinheader for cable connection, board-stack-solution, etc.)
- **Design**
- **Material**
- **Process-Integration**

# PCB Characteristics



- **Base material**
- **Hole-assembly**  
(drilling diameter, Cu-Layer, surface)
- **Position-Tolerance**
- **Lamination and Layer-Qty.**
- **PCB Thickness**
- **Surfaces to support the press-in process**

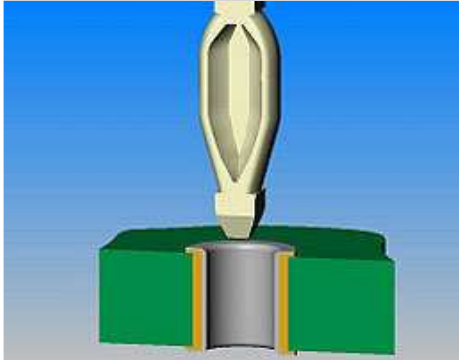


# Characteristics Insertion-Equipment **ept**



- Positioning of **assembly force** to components/contacts
- **Prevention of damages** of the PCB, contacts and components
- **Repeatability**
- **Cycletime**
- **Process controlled**
- **Integration** into manufacturing process

# Quality Parameters



## Contact resistance (<math><1\text{m}\Omega</math> / millivolt-method)

Retention force

Insertion force

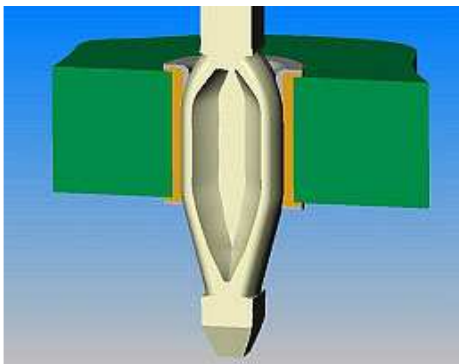
Prevention of tin chips

Minor pull down effect

Minor hole deformation

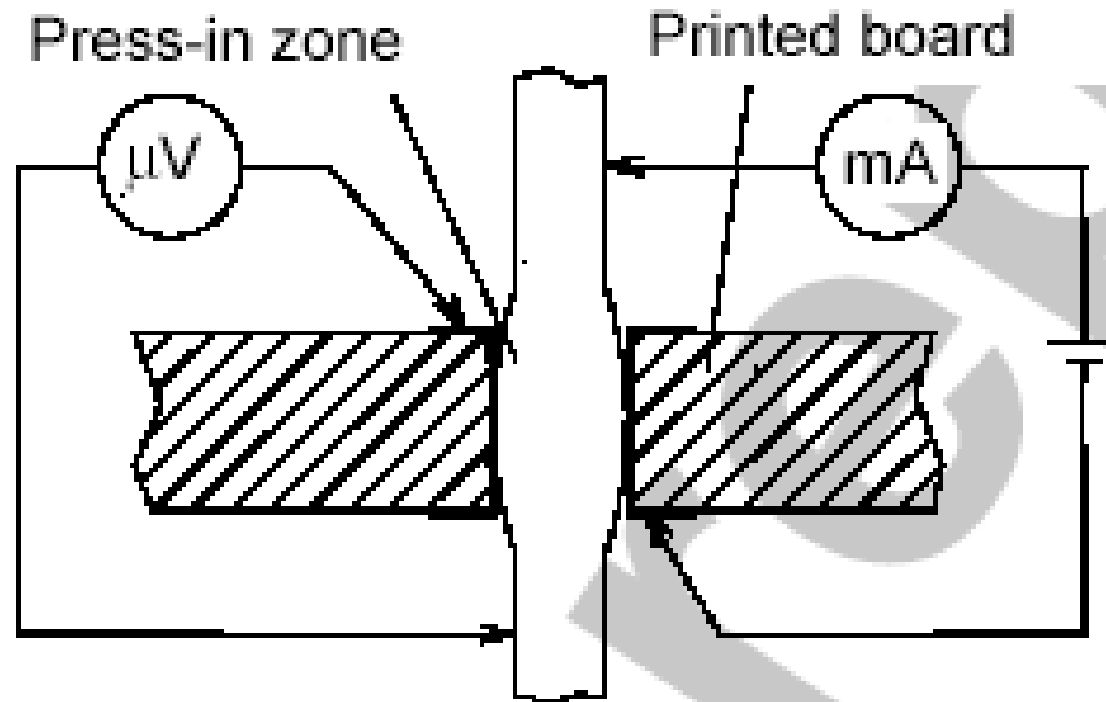
Obliquely positioned (pins)

Repairable

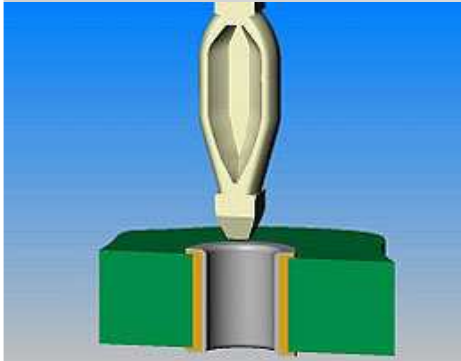


# Contact Resistance

## Measurable Contact Resistance



# Qualitätsmerkmale



Contact resistance (<math><1\text{m}\Omega</math> / millivolt-method)

## Retention force

Insertion force

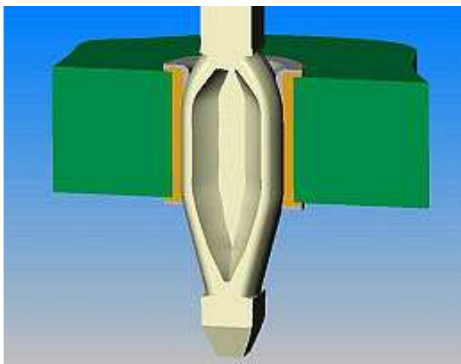
Prevention of tin chips

Minor pull down effect

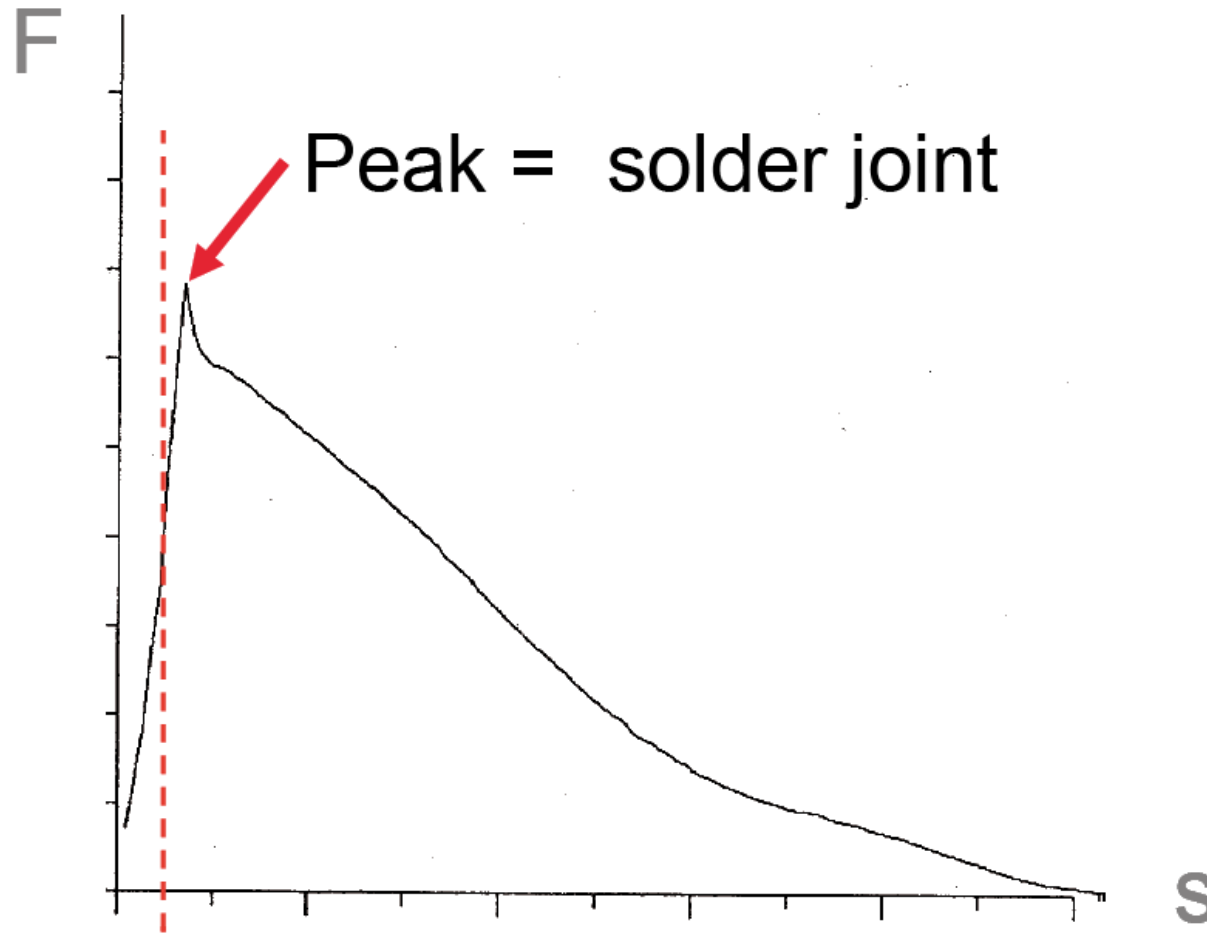
Minor hole deformation

Obliquely positioned (pins)

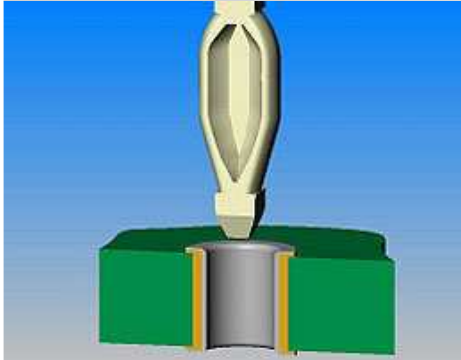
Repairable



# Retention Force (Peak)



# Quality Parameters



Contact resistance (<math><1\text{m}\Omega</math> / millivolt-method)

Retention force

## Insertion force

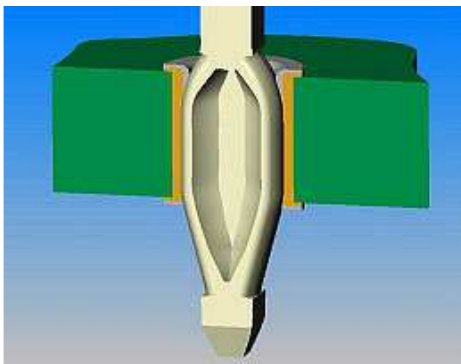
Prevention of tin chips

Minor pull down effect

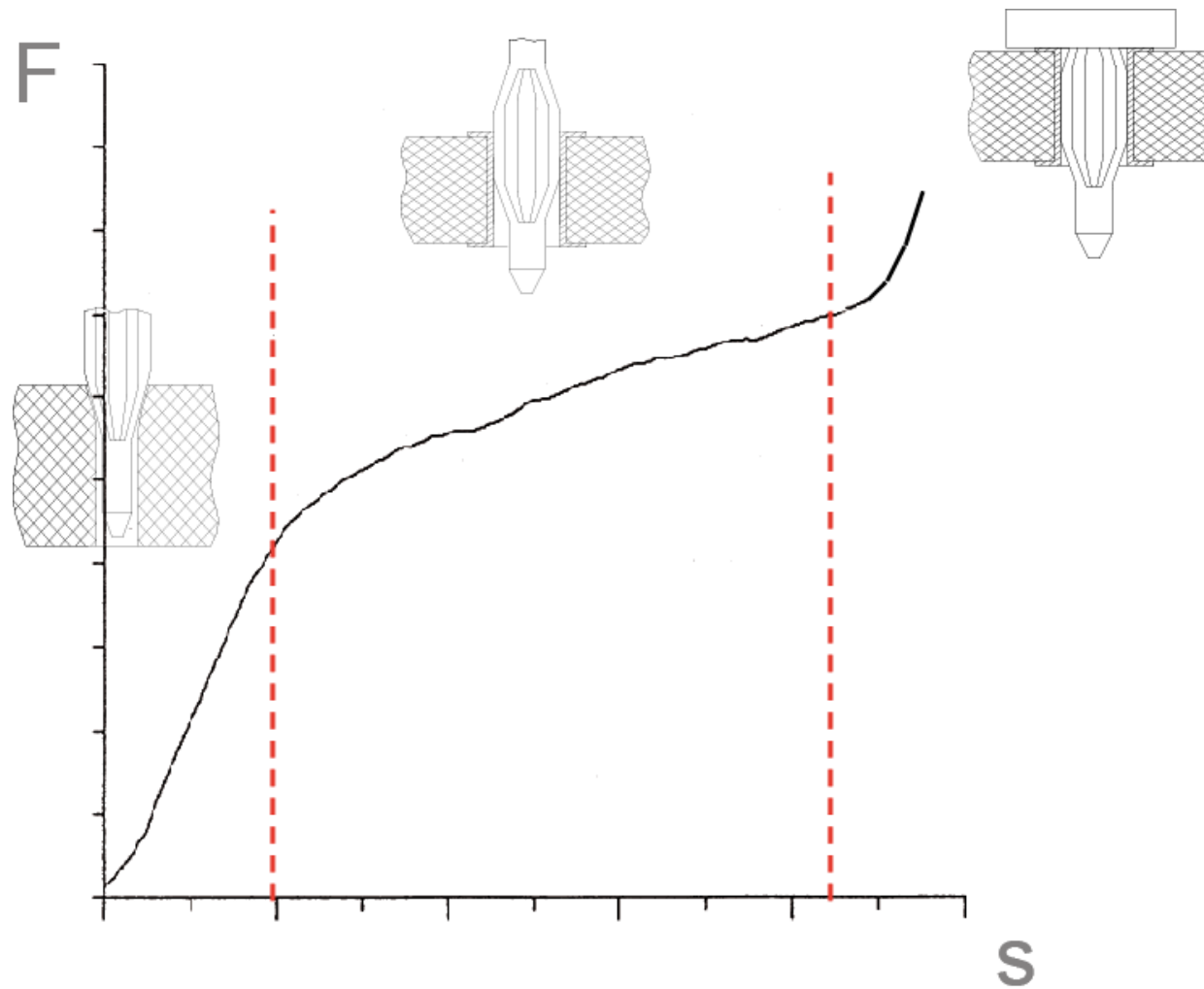
Minor hole deformation

Obliquely positioned (pins)

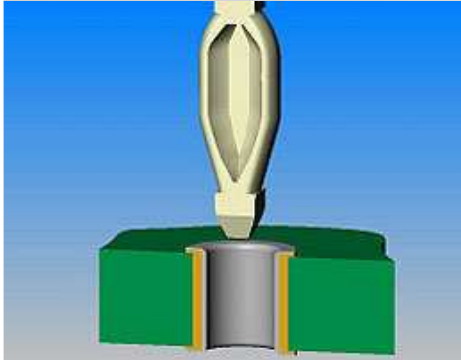
Repairable



# Insertion Force



# Quality Parameters



Contact resistance (<math><1\text{m}\Omega</math> / millivolt-method)

Retention force

Insertion force

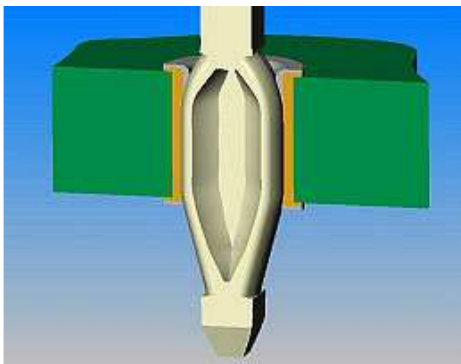
## Prevention of tin chips

Minor pull down effect

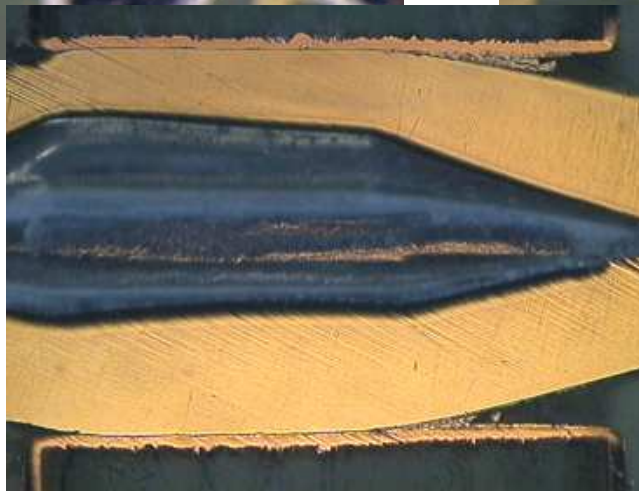
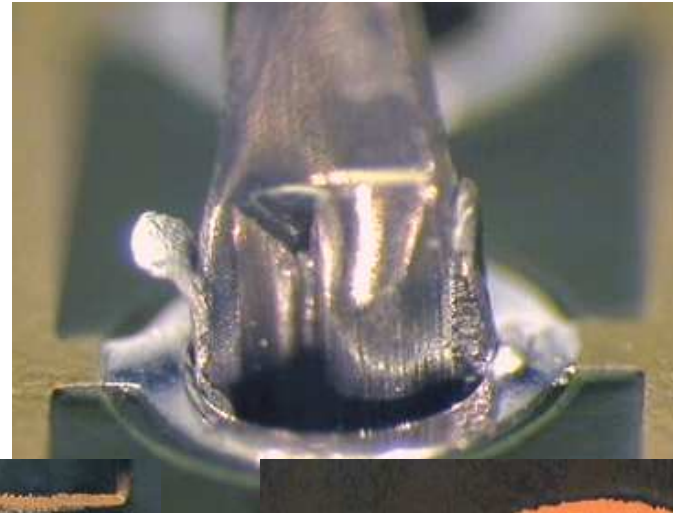
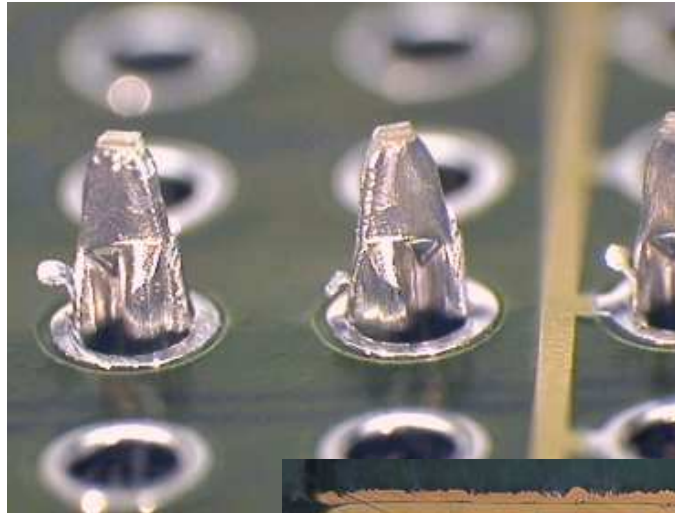
Minor hole deformation

Obliquely positioned (pins)

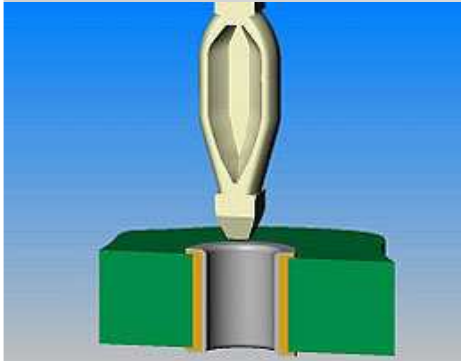
Repairable



# Prevention of Tin Chips



# Quality Parameters



Contact resistance (<math><1\text{m}\Omega</math> / millivolt-method)

Retention force

Insertion force

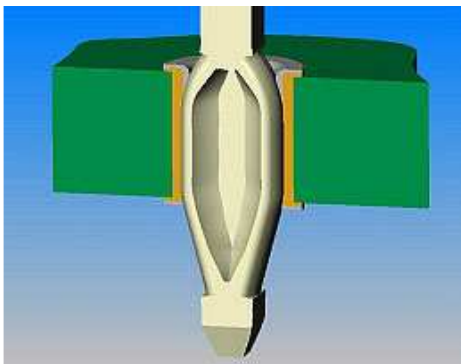
Prevention of tin chips

## Minor pull down effect

Minor hole deformation

Obliquely positioned (pins)

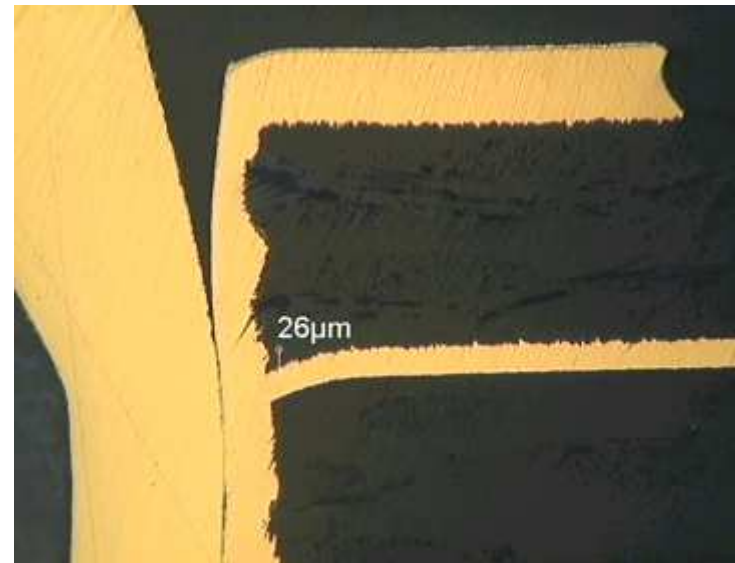
Repairable



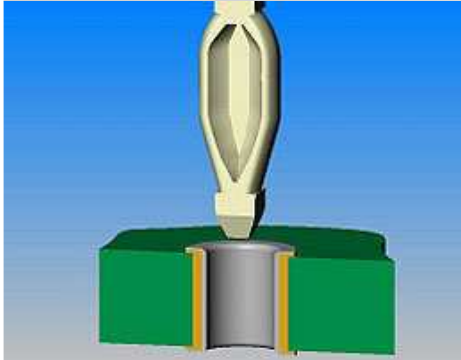
# Pull down Effect



Minor pull down effect



# Quality Parameters



Contact resistance (<math><1\text{m}\Omega</math> / millivolt-method)

Retention force

Insertion force

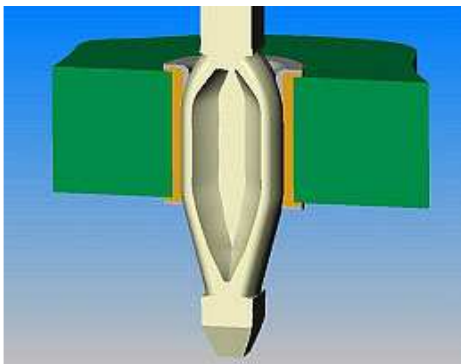
Prevention of tin chips

Minor pull down effect

## Minor hole deformation

Obliquely positioned (pins)

Repairable



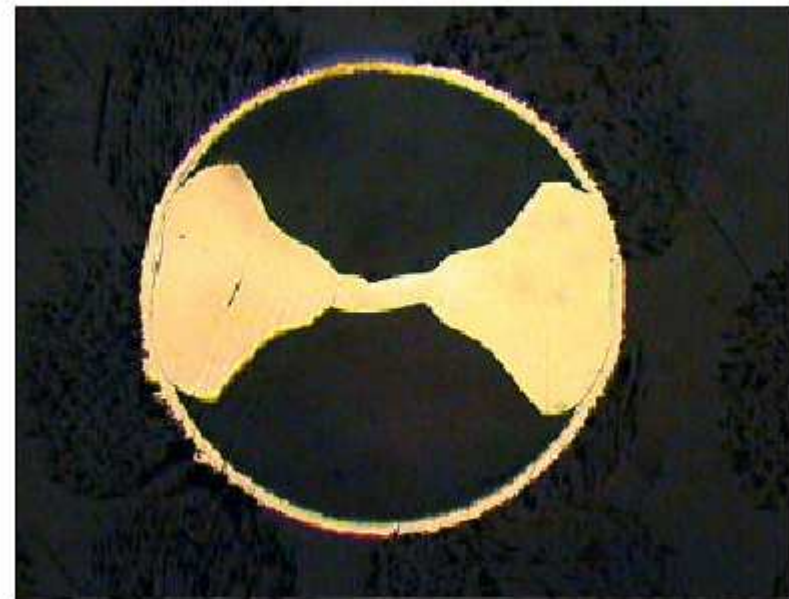
# Hole Deformation

## Minor hole deformation



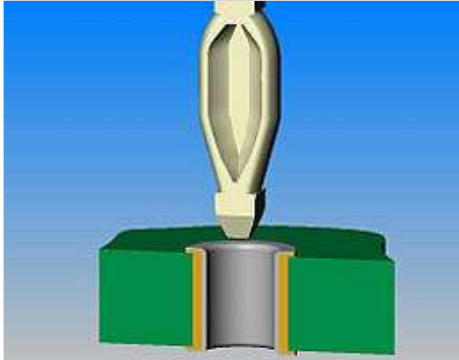
t=0,8mm

min. hole diameter



max. hole diameter

# Quality Parameters



Contact resistance (<math><1\text{m}\Omega</math> / millivolt-method)

Retention force

Insertion force

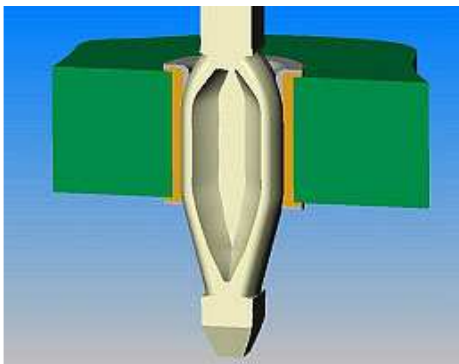
Prevention of tin chips

Minor pull down effect

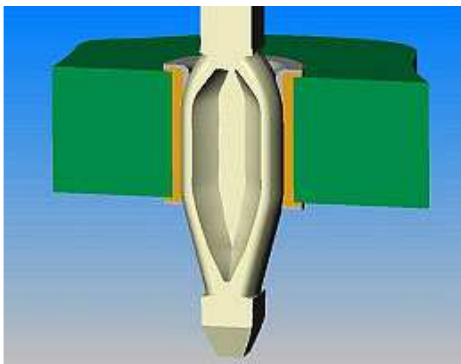
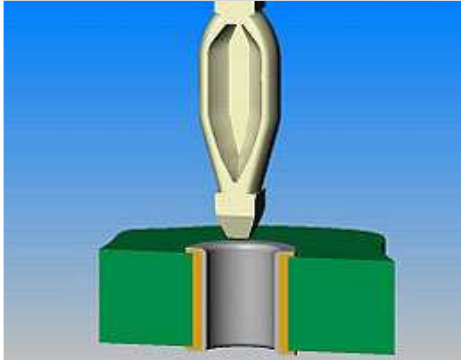
Minor hole deformation

**Obliquely positioned (pins)**

Repairable



# Quality Parameters



Contact resistance (<math><1\text{m}\Omega</math> / millivolt-method)

Retention force

Insertion force

Prevention of tin chips

Minor pull down effect

Minor hole deformation

Obliquely positioned (pins)

**Repairable**

# Amperage Capacity



- Current is not the problem, only the **resulting heat** is the cause of issue.
- The **press-fit pin is not** the critical element.
- The Connection is generally limited by the **glass-point of the PCB**

# Hightemperature Tests



- Reliable press-fit connections are possible in environments of **up to 150°C**
- **Standard Base materials** of contacts are usable
- PCB's with an **aligned glass-point (TG)** must be used
- Even **at 150°C** the retention force of the press-fit component does not vary very much when compared to ambient room temperature

- **Vibration:**

Such a tests, just with pins are useless, because there is almost no mass which will cause a force at acceleration. Such test are always performed in context with a certain application. Hence there is no standard reliability statement possible.

- **Retention force after temperature cycling:**

The criteria for the retention force are met even after more than 1.500 cycles between -40°C and +150°C (PCB's with proper TG)

- **Experience from real applications:**

ept sold in the last 10 years > 10 billion contacts in press-fit technology to the high demanding automotive industry, as of today ept has no reported field failure of the press-fit zone from customers.

